Transaction Information

Tool ID	BOND3
Tool Status	Running Wafers
Location	East Fishkill, USA
Wafer Size	300 mm
Fab Section	R&D
Tool Available Date	2024-12-31

General Product Information

Vendor Supplier	TEL
Model	TEL SYNAPSE V BONDER
Vintage	2013
Serial No	B120008
Asset Description	3D14 TEL SYNAPSE V BONDER BOND3
Software Version	Standard
CIM	SECS GEM
Process	Wafer Bonding

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Handler System	Standard	1	OK
Factory Interface	FOUP	5	
Options System			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status
NONE		

Missing/Faulty Parts / Accesorries List

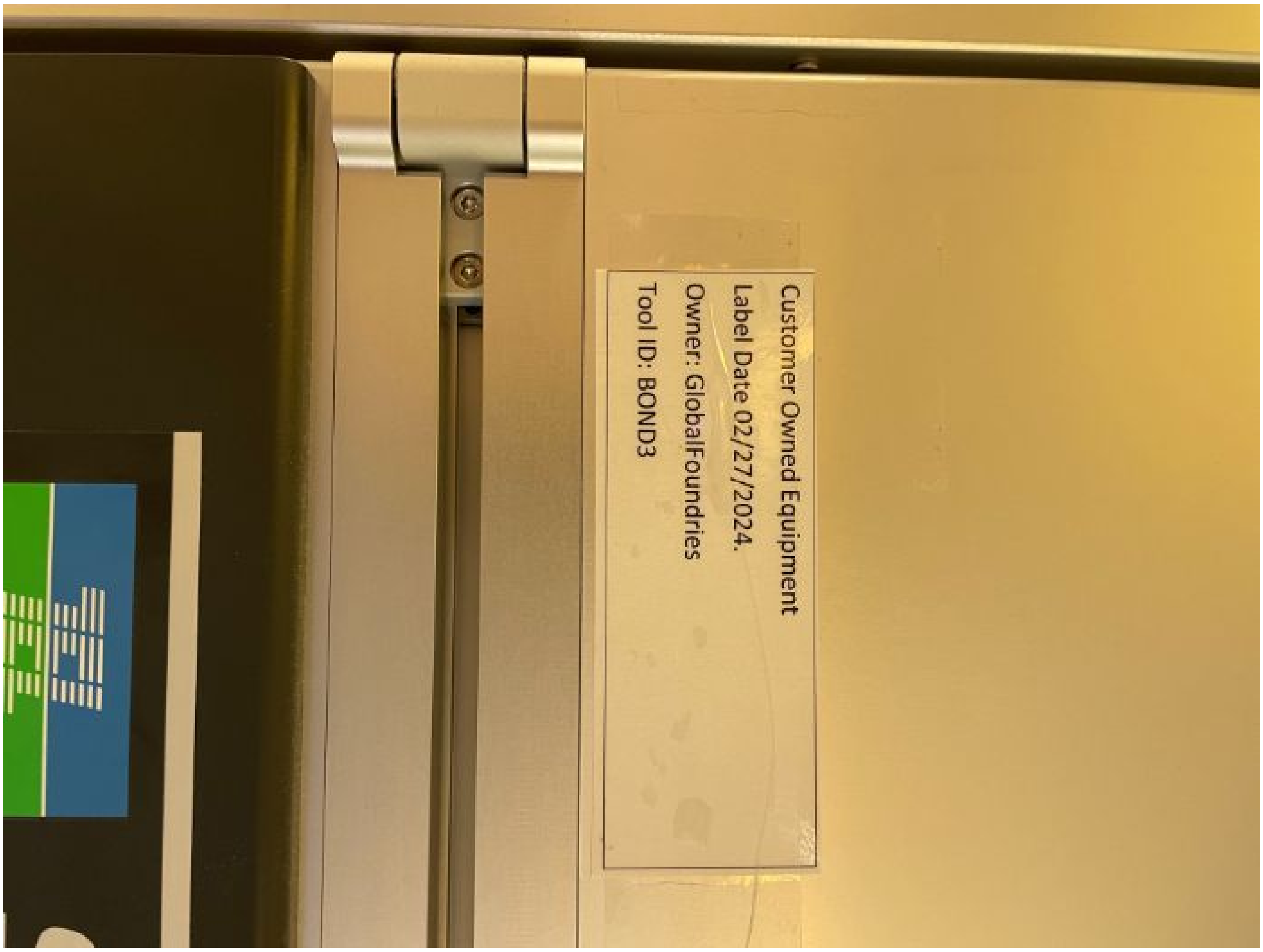
Description	Quantity
NONE	

Tool Pictures

General	Main tool

General	Main tool

General	Main tool



Customer Owned Equipment
Label Date 02/27/2024.
Owner: GlobalFoundries
Tool ID: BOND3

Additional Tool Data Files